

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg	
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03814	10.0	0.75563	
	Silver alloy	Silver (Ag)	7440-22-4	0.00763	2.0	0.15113	
	Lead alloy	Lead (Pb)	7439-92-1	0.33564	88.0	6.64957	
Subtotal				0.38141	100	7.55633	
Die		Silicon (Si)	7440-21-3	0.65239	100.0	12.925	
	Subtotal				0.65239	100	12.925
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.20193	100.0	4.00047	
	Subtotal				0.20193	100	4.00047
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.1765	7.7	43.12	
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.39195	12.0	67.2	
	Filler	Silica fused	60676-86-0	22.61299	80.0	448	
	Carbon Black	Carbon black	1333-86-4	0.0848	0.3	1.68	
	Subtotal				28.26624	100	560
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02084	0.03	0.4128	
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.75011	1.08	14.8608	
	Iron-nickel alloy	Copper (Cu)	7440-50-8	68.6138	98.79	1,359.3504	
	Subtotal				69.38475	99.9	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04383	100.0	20.68	
	Subtotal				1.04383	100	20.68
	Total				99.93055	100	NaN

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